

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2825947

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	JHON JHY LIAW	07/13/2009
RECEIVING PARTY DATA		
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	
Street Address:	NO. 8, LI-HSIN RD. VI, HSINCHU SCIENCE PARK	
City:	HSINCHU	
State/Country:	TAIWAN	
Postal Code:	300	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	14259585
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NAME OF SUBMITTER:	RANDY A. NORANBROCK	
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DATE SIGNED:	04/23/2014	
Total Attachments: 1		
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TSMC2008-0930

Docket No.: T5057-R019

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- 1) Jhon Jhy LIAW
- 2)
- 3)

who has made a certain new and useful invention, hereby sells, assigns and transfers unto **TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.** having a place of business at **No. 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-77**

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

MEMORY CIRCUITS AND ROUTING OF METAL LAYERS THEREOF

(a) for which an application for United States Letters Patent was filed on January 15, 2009, and identified by United States Patent Application No. 61/144,966; or

(b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Jhon Jhy LIAW
Name: Jhon Jhy LIAW

7/13 2009
Date:

2) _____
Name:

Date:

3) _____
Name:

Date: